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DISCRETE SEMICONDUCTORS

DATA SHEET



1N914; 1N914A; 1N914B High-speed diodes

Product specification Supersedes data of 1999 May 26 2003 Jun 06





High-speed diodes

1N914; 1N914A; 1N914B

FEATURES

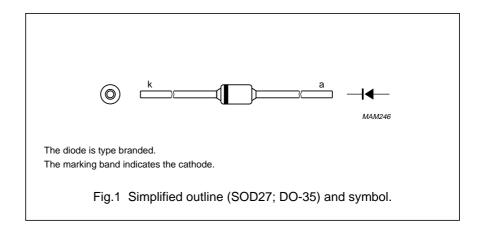
- Hermetically sealed leaded glass SOD27 (DO-35) package
- High switching speed: max. 4 ns
- Continuous reverse voltage: max. 75 V
- Repetitive peak reverse voltage: max. 100 V
- Repetitive peak forward current: max. 225 mA.

APPLICATIONS

· High-speed switching.

DESCRIPTION

The 1N914, 1N914A and 1N914B are high-speed switching diodes fabricated in planar technology, and encapsulated in a hermetically sealed leaded glass SOD27 (DO-35) package.



LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	RAMETER CONDITIONS		MAX.	UNIT
V _{RRM}	repetitive peak reverse voltage		_	100	V
V _R	continuous reverse voltage		_	75	V
I _F	continuous forward current	see Fig.2; note 1	_	75	mA
I _{FRM}	repetitive peak forward current		_	225	mA
I _{FSM}	non-repetitive peak forward current	square wave; T _j = 25 °C prior to surge; see Fig.4			
		t = 1 μs	-	4	A
		t = 1 ms	_	1	Α
		t = 1 s	_	0.5	A
P _{tot}	total power dissipation	T _{amb} = 25 °C; note 1	_	250	mW
T _{stg}	storage temperature		-65	+200	°C
Tj	junction temperature		_	175	°C

Note

1. Device mounted on an FR4 printed-circuit board; lead length 10 mm.

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ELECTRICAL CHARACTERISTICS

 $T_i = 25$ °C; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _F	forward voltage	see Fig.3			
	1N914; 1N914A	I _F = 10 mA	_	1	V
	1N914B	$I_F = 5 \text{ mA}$	0.62	0.72	V
	1N914B	I _F = 100 mA	_	1	V
I _R	reverse current	see Fig.5			
		V _R = 20 V	_	25	nA
		V _R = 75 V	_	5	μΑ
		V _R = 20 V; T _j = 150 °C	_	50	μΑ
C _d	diode capacitance	f = 1 MHz; V _R = 0; see Fig.6	_	4	pF
t _{rr}	reverse recovery time	when switched from I_F = 10 mA to I_R = 10 mA; R_L = 100 Ω ; measured at I_R = 1 mA; see Fig.7	_	8	ns
		when switched from I_F = 10 mA to I_R = 60 mA; R_L = 100 Ω ; measured at I_R = 1 mA; see Fig.7	_	4	ns
V _{fr}	forward recovery voltage	when switched from $I_F = 50$ mA; $t_r = 20$ ns; see Fig.8	_	2.5	V

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th j-tp}	thermal resistance from junction to tie-point	lead length 10 mm	240	K/W
R _{th j-a}	thermal resistance from junction to ambient	lead length 10 mm; note 1	500	K/W

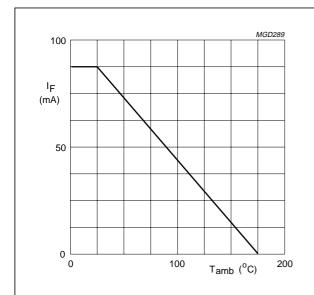
Note

1. Device mounted on a printed-circuit board without metallization pad.

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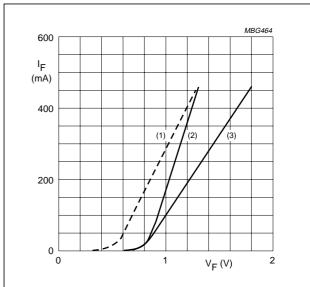
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GRAPHICAL DATA



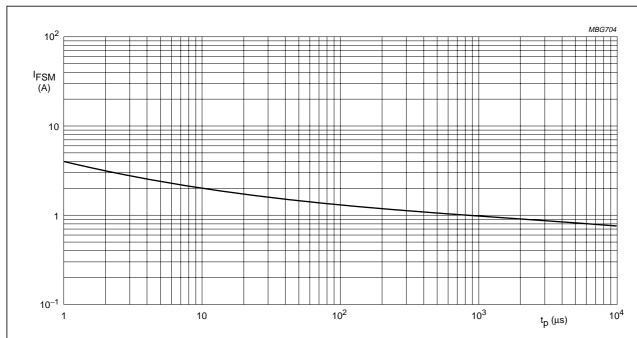
Device mounted on an FR4 printed-circuit board; lead length 10 mm.

Fig.2 Maximum permissible continuous forward current as a function of ambient temperature.



- (1) $T_j = 175$ °C; typical values.
- (2) $T_j = 25$ °C; typical values.
- (3) $T_j = 25$ °C; maximum values.

Fig.3 Forward current as a function of forward voltage.



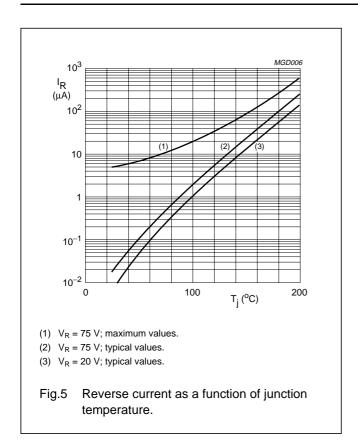
Based on square wave currents.

 T_j = 25 °C prior to surge.

Fig.4 Maximum permissible non-repetitive peak forward current as a function of pulse duration.

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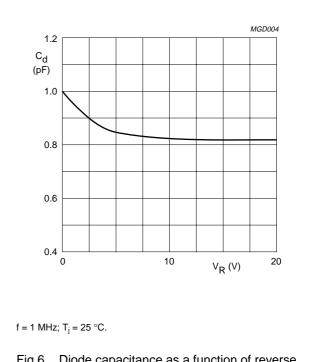


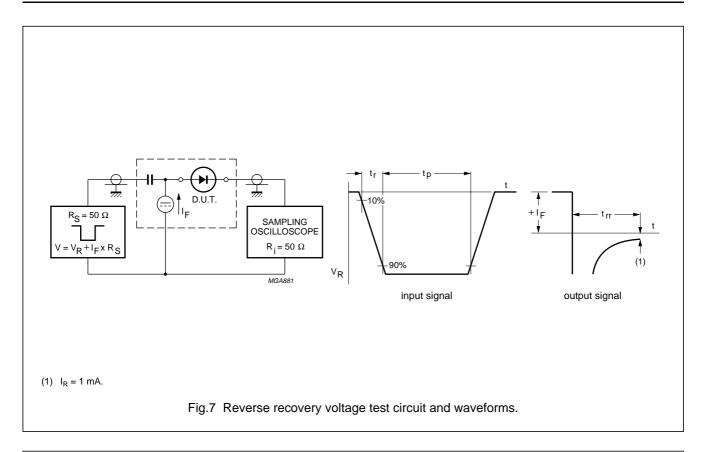
Fig.6 Diode capacitance as a function of reverse voltage; typical values.

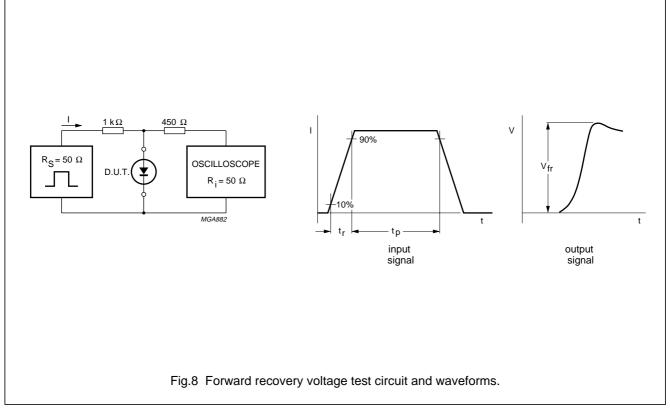
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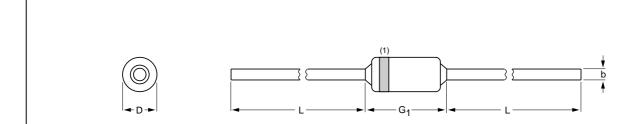
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PACKAGE OUTLINE

Hermetically sealed glass package; axial leaded; 2 leads

SOD27



DIMENSIONS (mm are the original dimensions)

UNIT	UNIT b max.		G ₁ max.	L min.	
mm	0.56	1.85	4.25	25.4	

0 1 2 mm scale

Note

1. The marking band indicates the cathode.

OUTLINE		REFER	ENCES	EUROPEAN ISSUE DATE	
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE
SOD27	A24	DO-35	SC-40		97-06-09

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DATA SHEET STATUS

LEVEL	DATA SHEET STATUS ⁽¹⁾	PRODUCT STATUS(2)(3)	DEFINITION
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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NOTES

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NOTES

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